

EPO-TEK® 301

Technical Data Sheet For Reference Only Spectrally Transparent Epoxy

Date: September 2017 Recommended Cure: 65°C / 2 Hours

Rev: X
No. of Components: Two

Mix Ratio by Weight: 20:5

Specific Gravity: Part A: 1.15 Part B: 0.87

Pot Life: 1-2 Hours

Shelf Life- Bulk: One year at room temperature

Minimum Alternative Cure(s):

May not achieve performance properties listed below

65°C / 1 Hour 23°C / 24 Hours

NOTES:

• Container(s) should be kept closed when not in use.

- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- TOTAL MASS SHOULD NOT EXCEED 25 GRAMS

<u>Product Description:</u> EPO-TEK® 301 is a two component, room temperature curing epoxy featuring very low viscosity, and excellent optical-mechanical properties.

<u>Typical Properties:</u> Cure condition: Varies as required Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Clear/C	olorless Part B: Clear/Colorless
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	100 - 200	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 65	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg	39	x 10 ⁻⁶ in/in°C
Above Tg	: 98	x 10 ⁻⁶ in/in°C
Shore D Hardness:	85	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	430	°C
Weight Loss:		
@ 200°C	0.12	%
@ 250°C	: 0.13	%
@ 300°C	0.39	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	436,249	psi
* Particle Size:	N/A	

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	N/A			
Volume Resistivity @ 23°C:	$\geq 1 \times 10^{13}$	Ohm-cm		
Dielectric Constant (1KHz):	4.00			
Dissipation Factor (1KHz):	0.016			

OPTICAL PROPERTIES @ 23°C	D:	
Spectral Transmission:	≥ 99% @ 382-980	nm
	≥ 97% @ 980-1,640	nm
	≥ 95% @ 1,640-2,040	nm
Refractive Index:	1.519 @ 589	nm



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EPO-TEK® 301 Advantages & Suggested Application Notes:

- Semiconductor: optical glob top or underfill; adhesion to common wafer passivation, solder mask and flex circuits; compatible with LED die, Si, GaAs.
- PCB: general potting and protection over FR4, flex, or ceramic PCBs.
- Fiber Optic:
 - Adhesive for glass and plastic fibers; wicking into fiber bundles used in patch cords, endoscopes or sensor devices; adhesive/seal/encapsulant used for fiber packaging and components; transmission of IR up to 2500 nm; terminating fibers into ferrules; fiber coupling and splicing.
- Opto-electronic:
 - LCD/LED adhesive for laminating glass layers; adhesion to PET plastic; general potting, encapsulation, and protection; spectral transmission in VIS and IR light; adhesive/encapsulant for VCSEL's packaged devices; resisting yellowing per ASTM D1925; adhesive for precision optics including lens, prism, beam splitter cubes, mirrors, and diodes, found in medical, university, or research communities.
- NASA approved, low outgassing epoxy http://outgassing.nasa.gov/